# **Bluetooth Module Datasheet**

Model: SJR-BTM383

**Version: V1.0** 

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## 1 Introduction

**Sky Jiarun Technologies** introduces the pioneer of the Bluetooth 5.3 modules SJR-BTM383 which is a high performance, cost effective, low power and compact solution. The Bluetooth module provides a complete 2.4GHz Bluetooth system based on the QCC3083 WLCSP chipset which is a single chip radio and baseband IC for Bluetooth 2.4GHz systems. This module is fully qualified single-chip dual mode Bluetooth@v5.3 system.

### 2 Key Features

### BTM383(QCC3083) Features

- Qualified to Bluetooth v5.3 specification
- 240 MHz Qualcomm® Kalimba™ audio DSP
- 32/80 MHz Developer Processor for applications
- Firmware Processor for system
- Flexible QSPI flash programmable platform
- High-performance 24-bit stereo audio interface
- Digital and analog microphone interfaces
- Flexible PIO controller and LED pins with PWM support
- Serial interfaces: UART, Bit Serializer (I<sup>2</sup> C/SPI), USB 2.0
- Advanced audio algorithms
- Qualcomm® aptX™ and aptX HD Audio
- aptX Adaptive, enabled using license key
- 1-mic Qualcomm® cVc™ speaker noise reduction and echo cancellation technology
- Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger
- 134-ball 6.7 mm x 7.4 mm x 1.0 mm, 0.5 mm pitch VFBGA

#### **Application subsystem**

- Dual-core application subsystem 32/80MHz operation
- 32-bit Firmware Processor (reserved for system use) executes:
  - Bluetooth upper stack
  - Profiles
  - House-keeping code
- 32-bit Developer Processor executes:
  - Developer applications
- Both cores execute code from external flash memory using QSPI clocked at 32 MHz or 80 MHz
- On-chip caches per core enable optimized performance and power consumption

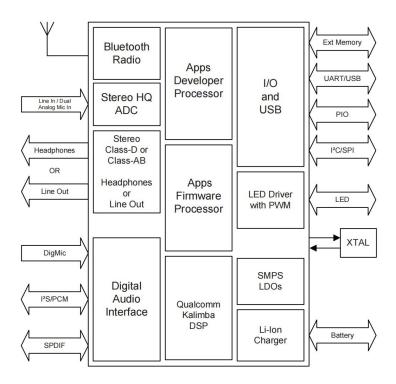
### **Bluetooth subsystem**

- Qualified to Bluetooth v5.3 specification including 2 Mbps Bluetooth Low Energy and Bluetooth Low Energy Isochronous Channels
- Qualcomm® Bluetooth High Speed Link
- Single ended antenna connection with on-chip balun and Tx/Rx switch
- Bluetooth, Bluetooth Low Energy, and mixed topologies supported
- Class 1 support

# **3 Applications**

Wired/wireless stereo headsets/headphones/speaker

## **4 Block Diagram**

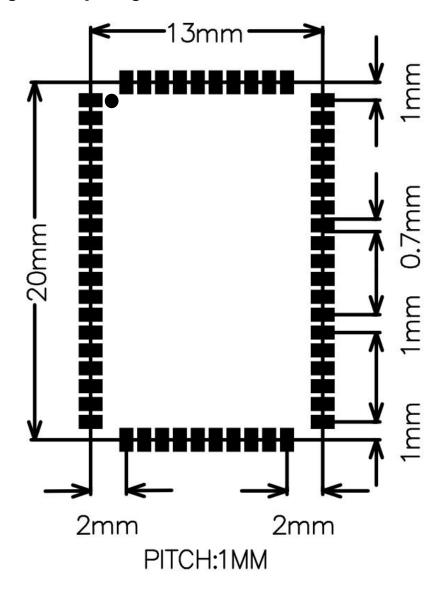


# **5 General specifications**

Model Name	SJR-BTM383
Product Description	Bluetooth 5.3 Class1.5 Module
Bluetooth Standard	Bluetooth 5.3
Chipset	QCC3083 WLCSP
Dimension	13mm x 20mm x 2.8mm
Operating Conditions	
Voltage	2.8~4.3V
Temperature	-40∼+85℃
Storage Temperature	-40∼+85℃
<b>Electrical Specifications</b>	
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	13dBm
π /4 DQPSK Receive Sensitivity	-94dBm
8DPSK Receive Sensitivity	-88dBm

# **6 Module Package Information**

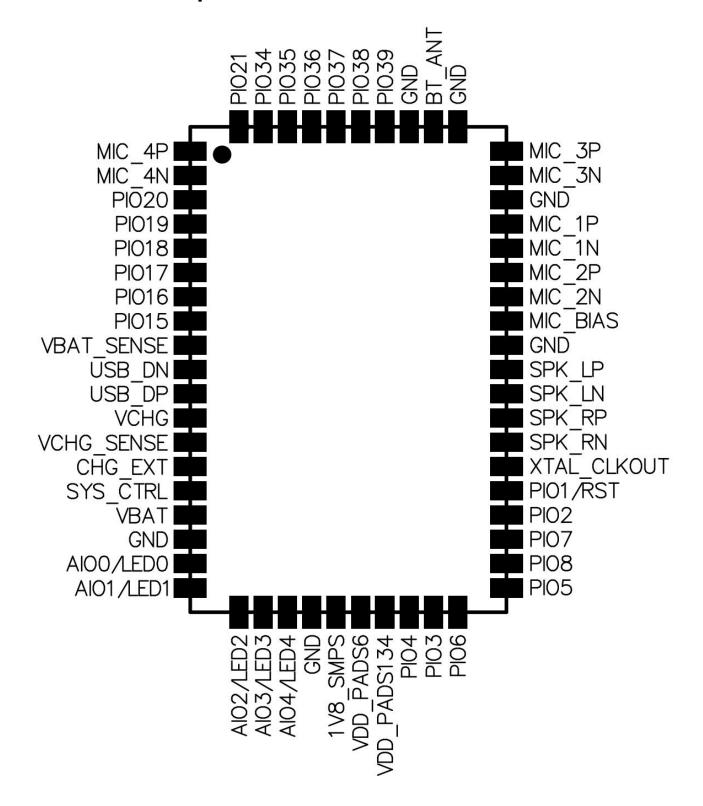
### **6.1 Pinout Diagram and package dimensions**



Unit: MM

**Recommended PCB layout footprint** 

### **6.2 Module Pin descriptions**



Pin#	Pin Name	Pin type	Description
			Microphone differential 4 input, positive.
1	MIC_4P	Analog	Alternative function:
			■ Differential audio line input 4,positive
			Microphone differential 4 input,negative.
2	MIC_4N	Analog	Alternative function:
			■ Differential audio line input 4,negative
		Digital: Bidirectional with	Programmable I/O line 20.
3	PIO[20]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DOUT[1]
		Digital: Bidirectional with	Programmable I/O line 19.
4	PIO[19]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DIN[0]
		Digital: Bidirectional with	Programmable I/O line 18.
5	PIO[18]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DOUT[0]
		Digital: Bidirectional with	Programmable I/O line 17.
6	PIO[17]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_SYNC
		Digital: Bidirectional with	Programmable I/O line 16.
7	PIO[16]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_CLK
		Digital: Bidirectional with	Programmable I/O line 15.
8	PIO[15]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ MCLK_OUT
9	VBAT_SENSE	Analog	Battery voltage sense input.
10	USB_DN	Digital	USB Full Speed device D- I/O.
11	USB_DP	Digital	USB Full Speed device D+ I/O.
12	VCHG	Supply	Supply to SMPS power switch from battery.
			Charger input sense pin. High
13	VCHG_SENSE	Analog	impedance. Connect VCHG_SENSE
			direct to SMPS_VCHG.
			External charger transistor current
	0110 51/5		control. Connect to base of external
14	CHG_EXT	Analog	charger transistor as per application
			schematic.
			Typically connected to an ON/OFF push
			button. If power is present from the
	SYS_CTRL		battery and/or charger, and software has
			placed the device in the OFF or
15		Digital input	DORMANT state, a button press boots
			the device. Also usable as a digital input
			in normal operation. No pull.
			Additional function:
1	1		■ PIO[0] input only

16	VBAT	Supply	Battery voltage input.
17	GND	Ground	Ground
		Analog or digital input/	General-purpose analog/digital input or
18	AIO0/LED0	open drain output.	open drain LED output.
		Analog or digital input/	General-purpose analog/digital input or
19	AIO1/LED1	open drain output.	open drain LED output.
		Analog or digital input/	General-purpose analog/digital input or
20	AIO2/LED2	open drain output.	open drain LED output.
0.4	A100# ED0	Analog or digital input/	General-purpose analog/digital input or
21	AIO3/LED3	open drain output.	open drain LED output.
00	A104# ED4	Analog or digital input/	General-purpose analog/digital input or
22	AIO4/LED4	open drain output.	open drain LED output.
23	GND	Ground	Ground
24	1V8_SMPS	Supply	1.8V voltage output.
25	VDD_PADS6	Supply	1.8 V/3.3 V PIO supply.
26	VDD_PADS134	Supply	1.8 V/3.3 V PIO supply.
		Digital: Bidirectional with	Programmable I/O line 4.
27	PIO[4]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MOSI[1]
		Digital: Bidirectional with	Programmable I/O line 3.
28	PIO[3]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[2]
		Digital: Bidirectional with	Programmable I/O line 6.
29	PIO[6]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MOSI[0]
		Digital: Bidirectional with	Programmable I/O line 5.
30	PIO[5]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[1]
		Digital: Bidirectional with	Programmable I/O line 8.
31	PIO[8]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_CLK
		Digital: Bidirectional with	Programmable I/O line 7.
32	PIO[7]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[0]
		Digital: Bidirectional with	Programmable I/O line 2.
33	PIO[2]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ TBR_MISO[3]
			Automatically defaults to
		Digital: Bidirectional with	RESET# mode when the device is unpowered, or in
34	PIO[1]/RST	programmable strength	off modes.
		internal pull-up/pull-down	Reconfigurable as a PIO after boot.
			Alternative function:
25	VTAL OLIVOUT	Anala -	■ Programmable I/O line 1
35	XTAL_CLKOUT	Analog	Buffered clock output.
36	SPK_RN	Analog	Headphone/speaker differential 2

			output, negative.
			Alternative function:
			■ Differential line output 2, negative
			Headphone/speaker differential 2
			output, positive.
37	SPK_RP	Analog	Alternative function:
			■ Differential line output 2, positive
			Headphone/speaker differential 1
38	SPK_LN	Analog	output, negative.
			Alternative function:
			■ Differential line output 1, negative
			Headphone/speaker differential 1
39	SPK_LP	Analog	output, positive.
			Alternative function:
			■ Differential line output 1, positive
40	GND	Ground	Ground
41	MIC_BIAS	Analog	Mic bias output.
			Microphone differential 2 input,
			negative.
42	MIC_2N	Analog	Alternative function:
			■ Differential audio line input 2,
			negative
			Microphone differential 2 input, positive.
43	MIC_2P	Analog	Alternative function:
	WIIO_21	, vitalog	■ Differential audio line input 2,
			positive
			Microphone differential 1 input,
		Analog	negative.
44	MIC_1N		Alternative function:
			■ Differential audio line input 1,
			negative
			Microphone differential 1 input, positive.
45	MIC_1P	Analog	Alternative function:
		, maiog	■ Differential audio line input 1,
			positive
46	GND	Ground	Ground
			Microphone differential 3 input,
	MIC_3N	Analog	negative.
47			Alternative function:
			■ Differential audio line input 3,
			negative
			Microphone differential 3 input, positive.
40	MIC_3P	Analog	Alternative function:
48			■ Differential audio line input 3,
			positive
	MIC_3N	Analog	Ground  Microphone differential 3 input, negative. Alternative function:  Differential audio line input 3, negative  Microphone differential 3 input, positive. Alternative function:

49	GND	Ground	Ground
50	BT_ANT	RF	Bluetooth transmit/receive.
51	GND	Ground	Ground
		Digital: Bidirectional with	Programmable I/O line 39.
52	PIO[39]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[3]
		Digital: Bidirectional with	Programmable I/O line 38.
53	PIO[38]	programmable strength	Alternative function:
		internal pull-up/pull-down	QSPI2_CS0#
		Digital: Bidirectional with	Programmable I/O line 37.
54	PIO[37]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[1]
		Digital: Bidirectional with	Programmable I/O line 36.
55	PIO[36]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[2]
		Digital: Bidirectional with	Programmable I/O line 35.
56	PIO[35]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_CLK
		Digital: Bidirectional with	Programmable I/O line 34.
57	PIO[34]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ QSPI2_IO[0]
		Digital: Bidirectional with	Programmable I/O line 21.
58	PIO[21]	programmable strength	Alternative function:
		internal pull-up/pull-down	■ PCM_DOUT[2]

## **7 Electrical Characteristics**

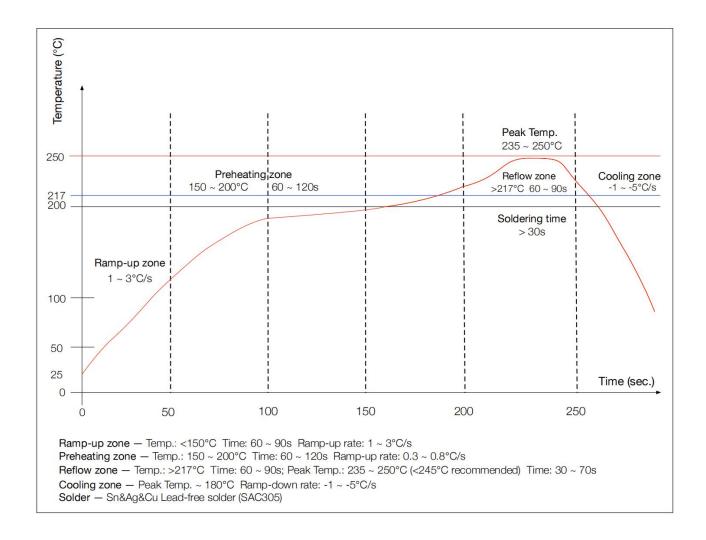
### 7.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	<b>-40</b> ℃	+85℃

### 7.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	<b>-40</b> ℃	+85°C
Supply voltage: VBAT	+2.8V	+4.3V

## 8 Recommended reflow temperature profile



The module Must go through 125  $^{\circ}$ C baking for at least 9 hours before SMT AND IR reflow process!

若拆封后未立即上线,天嘉润科技建议让下次上线前务必以 125℃烘烤 9 小时以上!

### **Record of Changes**

Data	Revision	Description
2023-02-01	V1.0	Original publication of this document.

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